

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS12887 (w/BR1225)	Oct-96	9640 A2	DALLAS	DA086747	N/A	24 MODULE

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Hi Temp Storage 85°C, No Bias P-18350	<u>48 Hr</u> 200/0	<u>Cum %</u> 0.0%
Temp Cycle 0°C to +70°C P-18418	<u>300 ~</u> <u>1K ~</u> 100/0 100/0	<u>Cum %</u> 0.0%
Biased Moisture 85°C/85% RH, 5.5 V. P-18419	<u>274 Hr</u> <u>959 Hr</u> 98/0 98/0	<u>Cum %</u> 0.0%
	Phys. Dimen. <u>P-18349</u> 6/0	Solderability <u>P-18348</u> 24/0

Failure Mode

Failure Analysis